

2FCY



533 Rec'd PCT/PTO 02 JUL 2002
Receipt

DOCKET NUMBER: 221608US0PCT/pmh

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:
Minoru TAKAYA, et al.

: GROUP: 1725

SERIAL NUMBER: 10/089,067

: ATTENTION:
Application Division
Customer Corrections

FILED: APRIL 05, 2002

FOR: SOLDERING FLUX, SOLDER PASTE AND METHOD OF SOLDERING

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The Patent Office is requested to provide a corrected Official Filing Receipt for the attached. No fees are required. If you have any questions, please do not hesitate to contact us.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

Norman F. Oblon
Attorney of Record
Registration Number 24,618

Roland E. Martin
Registration No. 48,082



22850

Tel. (703) 413-3000
Fax. (703) 413-2220
(OSMMN 10/98)



APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/089,067	04/05/2002	1725	1748	221608US0PCT	20	49	7

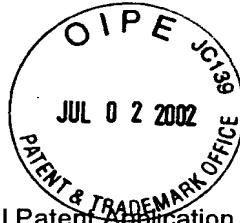
CONFIRMATION NO. 3041

22850
OBLON SPIVAK MCCLELLAND MAIER & NEUSTADT PC
FOURTH FLOOR
1755 JEFFERSON DAVIS HIGHWAY
ARLINGTON, VA 22202

FILING RECEIPT



OC000000008306223



Date Mailed: 06/19/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Minoru Takaya, Tokyo, JAPAN;
Hisayuki Abe, Tokyo, JAPAN;

Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP00/06957 10/05/2000

Foreign Applications

JAPAN 11/284859 10/05/1999
JAPAN 2000/83001 03/23/2000
JAPAN 2000/218046 07/18/2000

Projected Publication Date: Not Applicable, filed prior to November 29, 2000

Non-Publication Request: No

Early Publication Request: No

Title

Soldering flux, solder paste and method of soldering

Preliminary Class

228

RECEIVED: 6-24-02
OBLON, SPIVAK, MCCLELLAND
MAIER & NEUSTADT, P.C.
DOCKETING DEPT
Initials/Date Docketed: 427 6-26
Type of Resp(s):
Due Date(s):

PLEASE NOTE THAT THE NUMBER OF DRAWINGS IS INCORRECT. IT SHOULD READ AS FOLLOWS:

(DRAWINGS: 22)